

2N2907AHR

Hi-Rel PNP bipolar transistor 60 V - 0.6 A

Features

BV _{CEO}	60 V
I _C (max)	0.6 A
H _{FE} at 10 V - 150 mA	> 100
Operating temperature range	-65°C to +200°C

- Hi-Rel PNP bipolar transistor
- Linear gain characteristics
- ESCC qualified
- European preferred part list EPPL
- Radiation level: lot specific total dose contact marketing for specified level



The 2N2907AHR is a silicon planar epitaxial PNP transistor in TO-18 and LCC-3 packages. It is specifically designed for aerospace Hi-Rel applications and ESCC qualified according to the 5202-001 specification. In case of conflict between this datasheet and ESCC detailed specification, the latter prevails.

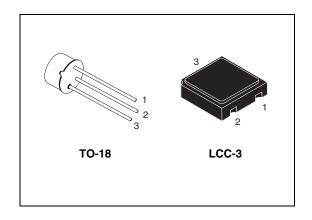


Figure 1. Internal schematic diagram

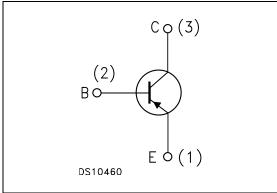


Table 1. Device summary

Order codes	Packages	Lead finish	Marking	Туре	EPPL	Packaging
2N2907AHR	TO-18	Gold Solder Dip	520200101 520100102	ESCC Flight		Strip pack
2N2907AT1	TO-18	Gold	2N2907AT1	Engineering model		Strip pack
SOC2907A	LCC-3	Gold	SOC2907A	Engineering model		Waffle pack
SOC2907AHRB	LCC-3	Gold Solder Dip	520200104 520200105	ESCC Flight	Yes	Waffle pack

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Electrical ratings 2N2907AHR

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{CBO}	Collector-base voltage (I _E = 0)	-60	V
V _{CEO}	Collector-emitter voltage (I _B = 0)	-60	V
V _{EBO}	Emitter-base voltage (I _C = 0)	-5	V
I _C	Collector current for 2N2907AHR for SOC2907AHRB	-0.6 -0.5	A A
P _{tot}	Total dissipation at $T_{amb} \le 25~^{\circ}\text{C}$ for 2N2907AHR for SOC2907AHRB for SOC2907AHRB (1) Total dissipation at $T_c \le 25~^{\circ}\text{C}$ for 2N2907AHR	0.4 0.4 0.73 1.8	W W W
T _{stg}	Storage temperature	-65 to 200	°C
TJ	Max. operating junction temperature	200	°C

^{1.} When mounted on a 15 x 15 x 0.6 mm ceramic substrate.

Table 3. Thermal data for through-hole package

Symbol	Parameter	TO-18	Unit
R _{thJC}	Thermal resistance junction-case max	97	°C/W
R_{thJA}	Thermal resistance junction-ambient max	437	°C/W

Table 4. Thermal data for SMD package

Symbol	Parameter	soc	Unit
R _{thJA}	Thermal resistance junction-ambient max Thermal resistance junction-ambient (1) max	437 240	°C/W

^{1.} When mounted on a 15 x 15 x 0.6 mm ceramic substrate.

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2 Electrical characteristics

 T_{case} = 25 °C unless otherwise specified.

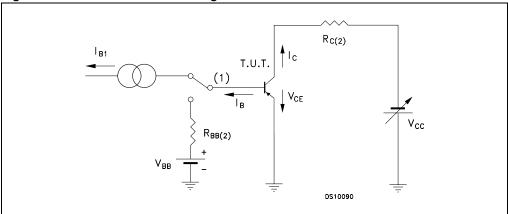
Table 5. Electrical characteristics

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{CBO}	Collector-base cut-off current (I _E = 0)	V _{CB} = -50 V V _{CB} = -50 V T _C = 150 °C			-10 -10	nΑ μΑ
V _{(BR)CBO}	Collector-base breakdown voltage (I _E = 0)	I _C = -10 μA	-60			V
V _{(BR)CEO} (1)	Collector-emitter breakdown voltage (I _B = 0)	I _C = -10 mA	-60			V
V _{(BR)EBO}	Emitter-base breakdown voltage (I _C = 0)	Ι _Ε = -10 μΑ	-5			V
V _{CE(sat)} (1)	Collector-emitter saturation voltage	I _C = -150 mA I _B = -15 mA			-0.4	V
V _{BE(sat)} (1)	Base-emitter saturation voltage	I _C = -150 mA I _B = -15 mA			-1.3	V
h _{FE} ⁽¹⁾	DC current gain	$\begin{split} &I_{C} = -0.1 \text{ mA} & V_{CE} = -10 \text{ V} \\ &I_{C} = -10 \text{ mA} & V_{CE} = -10 \text{ V} \\ &I_{C} = -150 \text{ mA} & V_{CE} = -10 \text{ V} \\ &I_{C} = -500 \text{ mA} & V_{CE} = -10 \text{ V} \end{split}$	75 100 100 50		300	
h _{fe}	Small signal current gain	$V_{CE} = -20 \text{ V}$ $I_{C} = -20 \text{ mA}$ $f = 100 \text{ MHz}$	2			
C _{CBO}	Output capacitance (I _E = 0)	$V_{CB} = -10 \text{ V}$ 100 kHz \le f \le 1 MHz			8	pF
t _{on}	Turn-on time	$V_{CC} = -30 \text{ V}$ $I_{C} = -150 \text{ mA}$ $I_{B1} = -15 \text{ mA}$			45	ns
t _{off}	Turn-off time	$V_{CC} = -30 \text{ V}$ $I_{C} = -150 \text{ mA}$ $I_{B1} = -I_{B2} = -15 \text{ mA}$			300	ns

^{1.} Pulsed duration = 300 μ s, duty cycle \leq 1.5%

2.1 Test circuit

Figure 2. Resistive load switching test circuit



- 1. Fast electronic switch
- 2. Non-inductive resistor



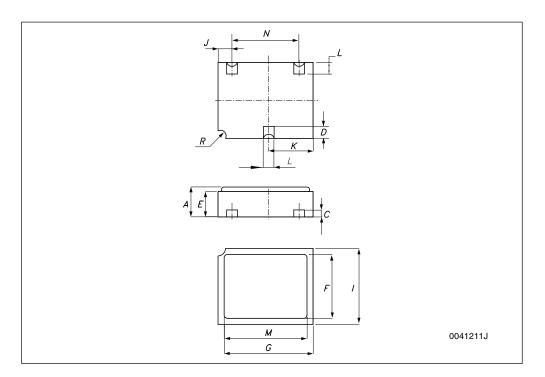
3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of $\mathsf{ECOPACK}^{\mathbb{B}}$ packages, depending on their level of environmental compliance. $\mathsf{ECOPACK}^{\mathbb{B}}$ specifications, grade definitions and product status are available at: $\mathit{www.st.com}$. $\mathsf{ECOPACK}^{\mathbb{B}}$ is an ST trademark.

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Ceramic Leadless Chip Carrier 3 mechanical data

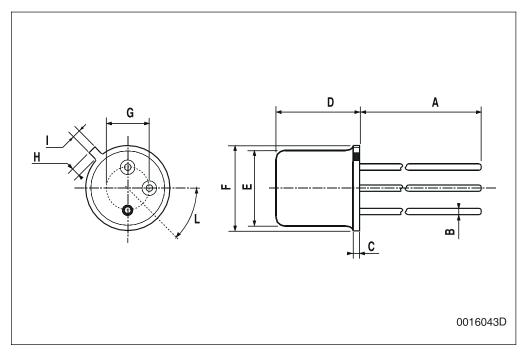
5.11			
DIM.	MIN.	TYP	MAX.
A	1.16		1.42
С	0.45	0.50	0.56
D		0.76	
Е		1	
F	1.90		2.15
G	2.90		3.25
I	2.40		2.74
J	0.40	0.57	0.80
К	1.35	1.52	1.75
L		0.50	
М	2.40		2.65
N		1.90	
R		0.30	





TO-18 Mechanical data

DIM.		mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
Α		12.7			0.500		
В			0.49			0.019	
D			5.3			0.208	
E			4.9			0.193	
F			5.8			0.228	
G	2.54			0.100			
Н			1.2			0.047	
I			1.16			0.045	
L	45°			45°			



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Revision history 2N2907AHR

4 Revision history

Table 6. Document revision history

Date	Revision	Changes
09-Feb-2009	1	Initial release
05-Jan-2010	2	Modified Table 1 on page 1

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